Negative Output Flyback Pulse Width Modulator

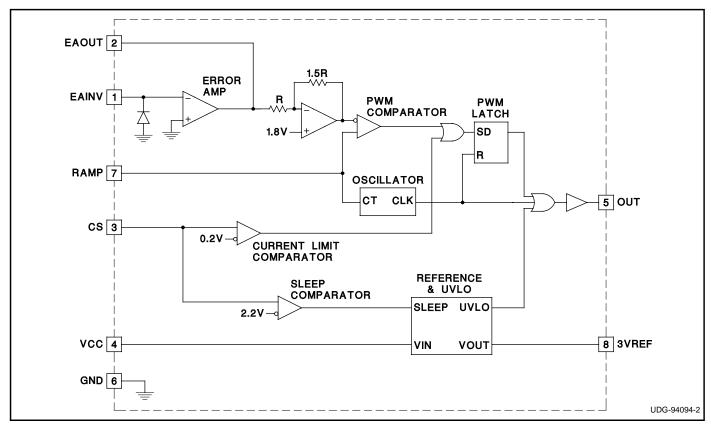
FEATURES

- Simple Single Inductor Flyback PWM for Negative Voltage Generation
- Drives External PMOS Switch
- Contains UVLO Circuit
- Includes Pulse-by-Pulse Current Limit
- Low 50μA Sleep Mode Current

DESCRIPTION

The UC3572 is a negative output flyback pulse width modulator which converts a positive input voltage to a regulated negative output voltage. The chip is optimized for use in a single inductor negative flyback switching converter employing an external PMOS switch. The block diagram consists of a precision reference, an error amplifier configured for voltage mode operation, an oscillator, a PWM comparator with latching logic, and a 0.5A peak gate driver. The UC3572 includes an undervoltage lockout circuit to insure sufficient input supply voltage is present before any switching activity can occur, and a pulse-by-pulse current limit. Output current can be sensed and limited to a user determined maximum value. The UVLO circuit turns the chip off when the input voltage is below the UVLO threshold. In addition, a sleep comparator interfaces to the UVLO circuit to turn the chip off. This reduces the supply current to only $50\mu\text{A}$, making the UC3572 ideal for battery powered applications.

BLOCK DIAGRAM

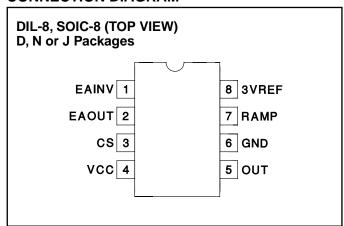


ABSOLUTE MAXIMUM RATINGS

VCC35V
EAINV0.6V to VCC
IEAOUT25mA
RAMP0.3V to 4V
CS0.3V to VCC
lout0.7A to 0.7A
13VREF
Storage Temperature65°C to +150°C
Junction Temperature65°C to +150°C
Lead Temperature (Soldering, 10 sec.)+300°C

Currents are positive into, negative out of the specified terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages.

CONNECTION DIAGRAM



ORDERING INFORMATION

		TEMPERATURE RANGE	PACKAGE
UC1	572	–55°C to +125°C	J
UC2	2572	-40°C to +85°C	D, N or J
UC	3572	0°C to +70°C	D or N

ELECTRICAL CHARACTERISTICS: Unless otherwise specified, VCC = 5V, CT = 680pF, T_A = T_J.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Reference Section				•	_
3VREF		2.94	3	3.06	V
Line Regulation	VCC = 4.75 to 30V		1	10	mV
Load Regulation	I3VREF = 0V to -5mA		1	10	mV
Oscillator Section					
Frequency	VCC = 5V to 30V	85	100	115	kHz
Error Amp Section					
EAINV	EAOUT = 2V	-10	0	10	mV
	IEANV = -1mA		-0.2	-0.9	V
IEAINV	EAOUT = 2V		-0.2	-1.0	μΑ
AVOL	EAOUT = 0.5V to 3V	65	90		dB
EAOUT High	EAINV = -100mV	3.6	4	4.4	V
EAOUT Low	EAINV = 100mV		0.1	0.2	V
I EAOUT	EAINV = -100mV, $EAOUT = 2V$	-350	-500		μΑ
	EAINV = 100mV, EAOUT = 2V	7	20		mA
Unity Gain Bandwidth	T _J = 25°C, F = 10kHz	0.6	1		MHz
Current Sense Comparator Section	1				
Threshold		0.185	0.205	0.225	V
Input Bias Current	CS = 0		-0.4	-1	μΑ
CS Propogation Delay			300		nS

ELECTRICAL CHARACTERISTICS: Unless otherwise specified, VCC = 5V, CT = 680pF, T_A = T_J.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Gate Drive Output Section		<u>.</u>			
OUT High Saturation	IOUT = 0		0	0.3	V
	IOUT = -10mA		0.7	1.5	V
	IOUT = -100mA		1.5	2.5	V
OUT Low Saturation	IOUT = 10mA		0.1	0.4	V
	IOUT = 100mA		1.5	2.2	V
Rise Time	$T_J = 25$ °C, CLOAD = 1nF + 3.3 Ohms		30	80	nS
Fall Time	$T_J = 25$ °C, CLOAD = 1nF + 3.3 Ohms		30	80	nS
Pulse Width Modulator Section					
Maximum Duty Cycle	EAINV = +100mV, VCC = 5V to 30V		92	96	%
Minimum Duty Cycle	EAINV = -100 mV, VCC = 5V to 30V			0	%
Modulator Gain	EAOUT = 1.5V to 2.5V	45	55	65	%/V
Undervoltage Lockout Section					
Start Threshold		3.5	4.2	4.5	V
Hysteresis		100	200	300	mV
Sleep Mode Section					
Threshold		1.8	2.2	2.6	V
Supply Current Section					
IVCC	VCC = 5V, 30V		9	15	mA
	VCC = 30, CS = 3V		50	150	μΑ

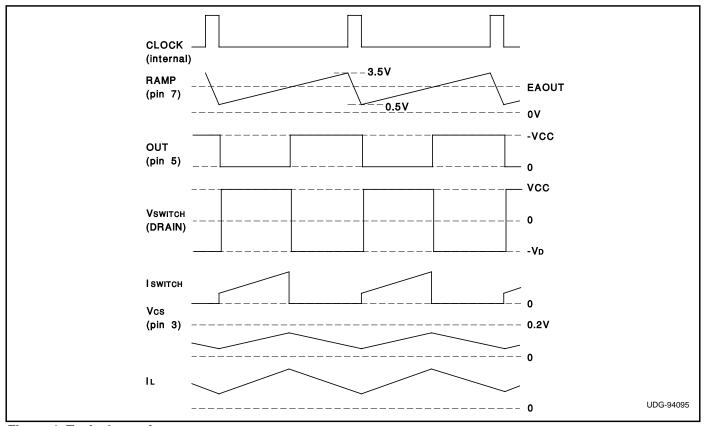


Figure 1. Typical waveforms.

PIN DESCRIPTIONS

3VREF: Precision 3V reference. Bypass with 100nF capacitor to GND.

CS: Current limit sense pin. Connect to a ground referenced current sense resistor in series with the flyback inductor. OUT will be held high (PMOS switch off) if CS exceeds 0.2V.

EAINV: Inverting input to error amplifier. Summing junction for 3VREF and VOUT sense. The non-inverting input of the error amplifier is internally connected to GND. This pin will source a maximum of 1mA.

EAOUT: Output of error amplifier. Use EAOUT and EAINV for loop compensation components.

GND: Circuit Ground.

OUT: Gate drive for external PMOS switch connected between Vcc and the flyback inductor. OUT drives the gate of the PMOS switch between Vcc and GND.

RAMP: Oscillator and ramp for pulse width modulator. Frequency is set by a capacitor to GND by the equation

$$F = \frac{1}{15k \bullet CRAMP}$$

Recommended operating frequency range is 10kHz to 200kHz.

VCC: Input voltage supply to chip. Range is 4.75 to 30V. Bypass with a $1\mu F$ capacitor.

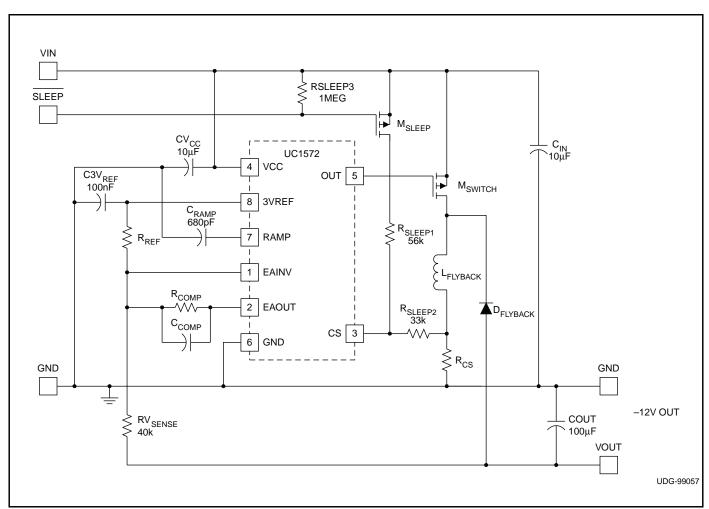


Figure 2. Typical application: +5V to -12V flyback converter.

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
			0010 (0) 10		.,	(4)	(5)	40 : 0=	
UC2572D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	UC2572D
UC2572D.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	UC2572D
UC2572DG4	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	UC2572D
UC2572DTR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	UC2572D
UC2572DTR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	UC2572D
UC3572D	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UC3572D
UC3572D.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UC3572D
UC3572DG4	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UC3572D
UC3572DTR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UC3572D
UC3572DTR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	UC3572D

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

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and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

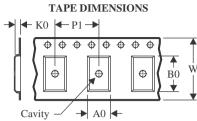
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

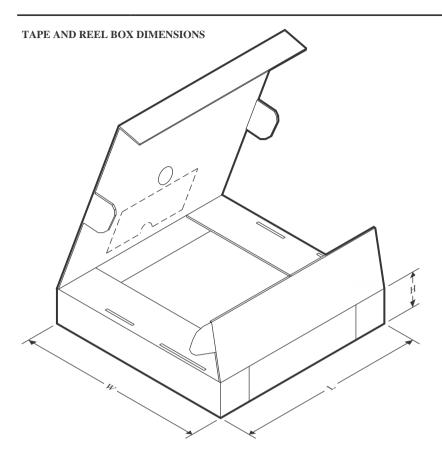
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
UC2572DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
UC3572DTR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
UC2572DTR	SOIC	D	8	2500	353.0	353.0	32.0
UC3572DTR	SOIC	D	8	2500	353.0	353.0	32.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
UC2572D	D	SOIC	8	75	507	8	3940	4.32
UC2572D.A	D	SOIC	8	75	507	8	3940	4.32
UC2572DG4	D	SOIC	8	75	507	8	3940	4.32
UC3572D	D	SOIC	8	75	507	8	3940	4.32
UC3572D.A	D	SOIC	8	75	507	8	3940	4.32
UC3572DG4	D	SOIC	8	75	507	8	3940	4.32

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